

GaAs INTEGRATED CIRCUIT $\mu PG2150T5L$

SP3T SWITCH FOR Bluetooth[™] AND 802.11b/g

DESCRIPTION

The μ PG2150T5L is a GaAs MMIC SP3T switch which was developed for Bluetooth and Wireless LAN.

This device can operate from 0.5 to 2.5 GHz, with low insertion loss and high isolation.

This device is housed in a 12-pin plastic TSQFN (<u>Thin Small Quad Flat Non-leaded</u>) package, which is suitable for high-density surface mounting.

FEATURES

Operation frequency	: f _{opt} = 0.5 to 2.5 GHz
 Control voltage 	: V _{cont (H)} = 2.3 to 3.6 V (2.85 V TYP.)
	: $V_{cont (L)} = -0.2$ to 0.2 V (0 V TYP.)
 Low insertion loss 	: Lins3 = 0.50 dB TYP. @ f = 2.5 GHz, ANT to RF1, 2, Vcont (H) = 2.85 V, Vcont (L) = 0 V
	: Lins6 = 0.60 dB TYP. @ f = 2.5 GHz, ANT to RF3, Vcont (H) = 2.85 V, Vcont (L) = 0 V
 High isolation 	: ISL3 = 35 dB TYP. @ f = 2.5 GHz, ANT to RF3, On port ANT to RF1, 2, RF1 to
	RF3, On port ANT to RF1, V_{cont} (H) = 2.85 V, V_{cont} (L) = 0 V
	: ISL6 = 18 dB TYP. @ f = 2.5 GHz, ANT to RF1, On port ANT to RF2, 3, ANT to
	RF2, On port ANT to RF1, 3, $V_{cont (H)} = 2.85 V$, $V_{cont (L)} = 0 V$
 Power handling 	: Pin (1 dB) = +31.0 dBm TYP. @ f = 2.5 GHz, ANT to RF1, 2, Vcont (H) = 2.85 V,
	V_{cont} (L) = 0 V
	: Pin (1 dB) = +25.0 dBm TYP. @ f = 2.5 GHz, ANT to RF3, V _{cont} (H) = 2.85 V,
	V_{cont} (L) = 0 V
 High density ourface mouth 	nting : 12 pin plastic TSOEN package (2.0 x 2.0 x 0.27 mm)

• High-density surface mounting : 12-pin plastic TSQFN package ($2.0 \times 2.0 \times 0.37$ mm)

APPLICATIONS

• Antenna switch for Bluetooth and 802.11b/g

ORDERING INFORMATION

Part Number	Order Number	Package	Marking	Supplying Form
<i>µ</i> PG2150T5L-E2	μPG2150T5L-E2-A	12-pin plastic TSQFN (Pb-Free)	2150	 Embossed tape 8 mm wide Pin 10, 11, 12 face the perforation side of the tape Qty 3 kpcs/reel

Remark To order evaluation samples, contact your nearby sales office. Part number for sample order: μ PG2150T5L-A

Caution Observe precautions when handling because these devices are sensitive to electrostatic discharge.

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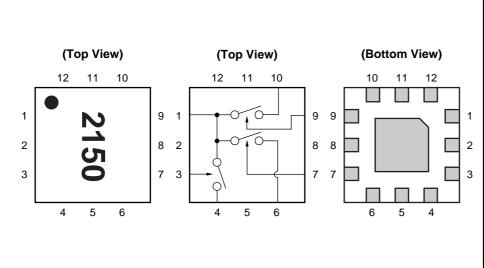
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The mark <R> shows major revised points.

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PIN CONNECTIONS AND INTERNAL BLOCK DIAGRAM



Pin No.	Pin Name
1	ANT
2	GND
3	V _{cont} 2
4	RF2
5	GND
6	RF3
7	V _{cont} 3
8	GND
9	Vcont1
10	RF1
11	N.C.
12	N.C.

Remark Exposed pad : GND

TRUTH TABLE

Vcont1	V _{cont} 2	V _{cont} 3	ANT-RF1	ANT-RF2	ANT-RF3
High	Low	Low	ON	OFF	OFF
Low	High	Low	OFF	ON	OFF
Low	Low	High	OFF	OFF	ON

ABSOLUTE MAXIMUM RATINGS (TA = +25°C, unless otherwise specified)

Parameter	Symbol	Ratings	Unit
Switch Control Voltage	Vcont	-6.0 to +6.0 Note	V
Input Power1 (ANT-RF1, ANT-RF2)	Pin1	+31.5	dBm
Input Power2 (ANT-RF3)	Pin2	+25.5	dBm
Operating Ambient Temperature	TA	-45 to +85	°C
Storage Temperature	Tstg	–55 to +150	°C

Note $|V_{cont (H)} - V_{cont (L)}| \le 6.0 V$

RECOMMENDED OPERATING RANGE (TA = +25°C, unless otherwise specified)

Parameter	Symbol	MIN.	TYP.	MAX.	Unit
Operating Frequency	fopt	0.5	ļ	2.5	GHz
Switch Control Voltage (H)	Vcont (H)	2.3	2.85	3.6	V
Switch Control Voltage (L)	Vcont (L)	-0.2	0	0.2	V

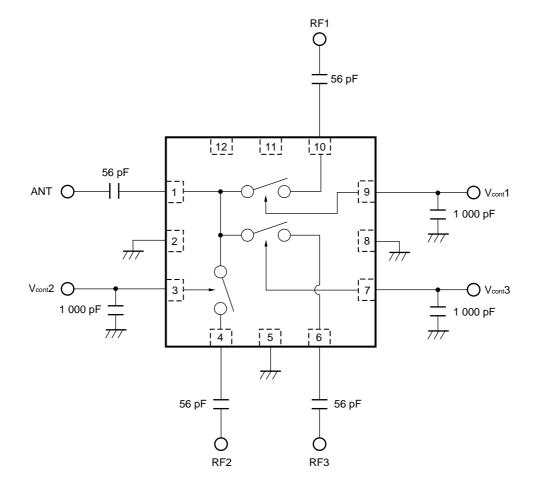
ELECTRICAL CHARACTERISTICS

(TA = +25°C, V_{cont} (H) = 2.85 V, V_{cont} (L) = 0 V, DC blocking capacitors = 56 pF, unless otherwise specified)

Parameter	Symbol	Pass	Test Conditions	MIN.	TYP.	MAX.	Unit
Insertion Loss 1	Lins1	ANT to RF1, 2	f = 0.5 to 1.0 GHz	-	0.40	0.55	dB
Insertion Loss 2	Lins2		f = 1.0 to 2.0 GHz	-	0.45	0.60	dB
Insertion Loss 3	Lins3		f = 2.0 to 2.5 GHz	-	0.50	0.65	dB
Insertion Loss 4	Lins4	ANT to RF3	f = 0.5 to 1.0 GHz	-	0.45	0.60	dB
Insertion Loss 5	Lins5		f = 1.0 to 2.0 GHz	-	0.55	0.70	dB
Insertion Loss 6	Lins6		f = 2.0 to 2.5 GHz	-	0.60	0.75	dB
Isolation 1	ISL1	ANT to RF3	f = 0.5 to 1.0 GHz	29	32	-	dB
		On port ANT to					
Isolation 2	ISL2	RF1, 2	f = 1.0 to 2.0 GHz	29	32	-	dB
		RF1 to RF3					
Isolation 3	ISL3	On port ANT to	f = 2.0 to 2.5 GHz	30	35	-	dB
		RF1					
Isolation 4	ISL4	ANT to RF1	f = 0.5 to 1.0 GHz	23	26	-	dB
		On port ANT to					
Isolation 5	ISL5	RF2, 3	f = 1.0 to 2.0 GHz	17	20	-	dB
		ANT to RF2					
Isolation 6	ISL6	On port ANT to	f = 2.0 to 2.5 GHz	15	18	-	dB
		RF1, 3					
Input Return Loss	RLin	ANT to RF1, 2, 3	f = 0.5 to 2.5 GHz	15	20	-	dB
Output Return Loss	RLout	ANT to RF1, 2, 3	f = 0.5 to 2.5 GHz	15	20	-	dB
1 dB Loss Compression	Pin (1 dB)	ANT to RF1, 2	f = 1.0 GHz	+28.0	+31.0	-	dBm
Input Power Note			f = 2.0 GHz	+28.0	+31.0	-	dBm
			f = 2.5 GHz	+28.0	+31.0	-	dBm
		ANT to RF3	f = 1.0 GHz	+22.0	+25.0	-	dBm
			f = 2.0 GHz	+22.0	+25.0	_	dBm
			f = 2.5 GHz	+22.0	+25.0	-	dBm
Switch Control Current	Icont	ANT to RF1, 2, 3	RF None	_	0.05	1.0	μA
Switch Control Speed	tsw	ANT to RF1, 2, 3	50% CTL to	_	50	_	ns
			90/10% RF				

Note Pin (1 dB) is the input power level when the insertion loss increases 1 dB more than that of linear the range.

EVALUATION CIRCUIT

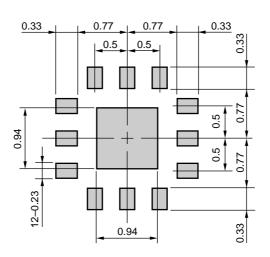


The application circuits and their parameters are for reference only and are not intended for use in actual design-ins.

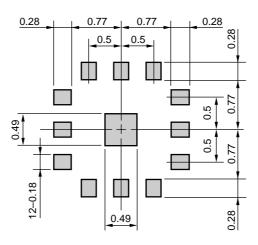
<R> MOUNTING PAD AND SOLDER PAD LAYOUT DIMENSIONS

12-PIN PLASTIC TSQFN (UNIT: mm)

MOUNTING PAD



SOLDER PAD

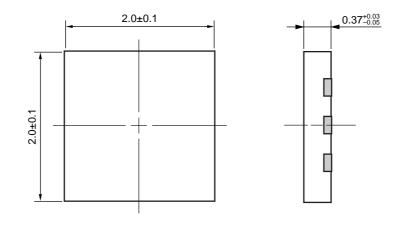




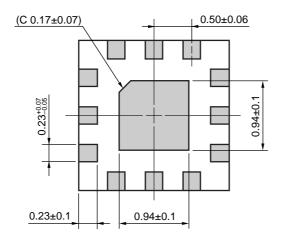
Remark The mounting pad and solder pad layouts in this document are for reference only.

PACKAGE DIMENSIONS

12-PIN PLASTIC TSQFN (UNIT: mm)



(Bottom View)



Remark (): Reference value

RECOMMENDED SOLDERING CONDITIONS

This product should be soldered and mounted under the following recommended conditions. For soldering methods and conditions other than those recommended below, contact your nearby sales office.

Soldering Method	Soldering Conditions		Condition Symbol
Infrared Reflow	Peak temperature (package surface temperature) Time at peak temperature Time at temperature of 220°C or higher Preheating time at 120 to 180°C Maximum number of reflow processes Maximum chlorine content of rosin flux (% mass)	: 260°C or below : 10 seconds or less : 60 seconds or less : 120±30 seconds : 3 times : 0.2%(Wt.) or below	IR260
Wave Soldering	Peak temperature (molten solder temperature) Time at peak temperature Preheating temperature (package surface temperature) Maximum number of flow processes Maximum chlorine content of rosin flux (% mass)	: 260°C or below : 10 seconds or less : 120°C or below : 1 time : 0.2%(Wt.) or below	WS260
Partial Heating	Peak temperature (terminal temperature) Soldering time (per side of device) Maximum chlorine content of rosin flux (% mass)	: 350°C or below : 3 seconds or less : 0.2%(Wt.) or below	HS350

Caution Do not use different soldering methods together (except for partial heating).

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M8E 02.11-1

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	• Follow related laws and ordinances when disposing of the product. If there are no applicable laws and/or ordinances, dispose of the product as recommended below.
	 Commission a disposal company able to (with a license to) collect, transport and dispose of materials that contain arsenic and other such industrial waste materials.
	2. Exclude the product from general industrial waste and household garbage, and ensure that the product is controlled (as industrial waste subject to special control) up until final disposal.
	• Do not burn, destroy, cut, crush, or chemically dissolve the product.
	• Do not lick the product or in any way allow it to enter the mouth.



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Lead (Pb)	< 1000 PPM	-A -AZ Not Detected (*)	
Mercury	< 1000 PPM	Not Detected	
Cadmium	< 100 PPM	Not Detected	
Hexavalent Chromium	< 1000 PPM	Not Detected	
РВВ	< 1000 PPM	Not Detected	
PBDE	< 1000 PPM	Not Detected	

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